Notice of References Cited Application/Control No. 10/803,502 Examiner Nicholas P. D'Aniello Applicant(s)/Patent Under Reexamination PAUL ET AL. Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	Α	US-5,564,620	10-1996	Rawers et al.	228/265
*	В	US-5,545,373	08-1996	Maziasz et al.	420/81
*	С	US-4,838,337	06-1989	Siemers, Paul A.	164/46
	D	US-			
	Е	US-			
	F	US-			
	G	US-			
	Ι	US-			
	-	US-			
	٦	US-			
	K	US-			
	┙	US-			
	М	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	0					
	Р					
	Q					
	R					
	S					
	Т					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)		
	U	Paul BK, Dewey T, Alman D, Wilson RD. Intermetallic microlamination for high-temperature reactors. In: Proceedings of the Fourth International Conference on Microreaction Technology, Atlanta, GA, 2000. p. 236–43.		
	٧	J. Duszczyk et al. "The Characteristics of the Diffusion Between the As-reaction- formed Ni3Al Intermetallic Compound and Pure Nickel for Interfacial Bonding" Journal of Materials Science Letters, Volume 18, Issue 2, Pages 111 - 113 Issue Cover Date - 1999-01-01		
	w			
	х			

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).) Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.